



MACMIC

December 2011

PRELIMINARY

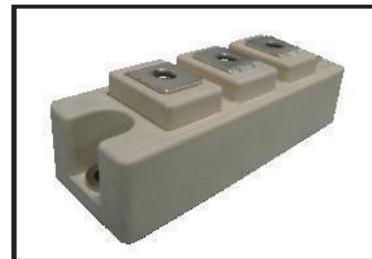
MMF200S170DA-DA2B

1700V 200A FRED Module

RoHS Compliant

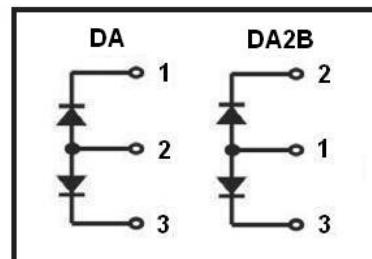
## PRODUCT FEATURES

- Ultrafast Reverse Recovery Time
- Soft Reverse Recovery Characteristics
- Low Reverse Recovery Loss
- Low Forward Voltage
- High Surge Current Capability
- Low Inductance Package



## APPLICATIONS

- Inversion Welder
- Uninterruptible Power Supply (UPS)
- Plating Power Supply
- Ultrasonic Cleaner and Welder
- Converter & Chopper
- Power Factor Correction (PFC) Circuit



## ABSOLUTE MAXIMUM RATINGS

T<sub>C</sub>=25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Values	Unit
V <sub>R</sub>	Maximum D.C. Reverse Voltage		1700	V
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage		1700	V
I <sub>F(AV)</sub>	Average Forward Current	T <sub>C</sub> =80°C, Per Diode	200	A
		T <sub>C</sub> =80°C, 20KHz, Per Diode	150	A
I <sub>F(RMS)</sub>	RMS Forward Current	T <sub>C</sub> =80°C, Per Diode	280	A
I <sub>FSM</sub>	Non-Repetitive Surge Forward Current	t=10ms, 50Hz, Sine	2000	A
		t=8.3ms, 60Hz, Sine	2200	A
I <sup>2</sup> t	I <sup>2</sup> t (For Fusing)	t=10ms, 50Hz, Sine	20000	A <sup>2</sup> s
		t=8.3ms, 60Hz, Sine	24200	A <sup>2</sup> s
P <sub>D</sub>	Power Dissipation		893	W
T <sub>J</sub>	Junction Temperature		-40 to +150	°C
T <sub>STG</sub>	Storage Temperature Range		-40 to +125	°C
V <sub>isol</sub>	Insulation Test Voltage	AC, t=1min	3000	V
Torque	Module-to-Sink	Recommended (M6)	3~5	N·m
Torque	Module Electrodes	Recommended (M6)	3~5	N·m
R <sub>θJC</sub>	Thermal Resistance	Junction-to-Case	0.14	°C /W
Weight			160	g

## ELECTRICAL CHARACTERISTICS

 $T_C=25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{RM}$	Reverse Leakage Current	$V_R=1700\text{V}$	--	--	5	mA
		$V_R=1700\text{V}, T_J=125^\circ\text{C}$	--	--	20	mA
$V_F$	Forward Voltage	$I_F=200\text{A}$	--	1.8	2.25	V
		$I_F=200\text{A}, T_J=125^\circ\text{C}$	--	1.95	--	V
$t_{rr}$	Reverse Recovery Time	$I_F=1\text{A}, V_R=30\text{V}, di_F/dt=-200\text{A}/\mu\text{s}$	--	120	--	ns
$t_{rr}$	Reverse Recovery Time	$V_R=850\text{V}, I_F=200\text{A}$	--	750	--	ns
$I_{RRM}$	Max. Reverse Recovery Current	$di_F/dt=-200\text{A}/\mu\text{s}, T_J=25^\circ\text{C}$	--	40	--	A
		$V_R=850\text{V}, I_F=200\text{A}$	--	1.4	--	$\mu\text{s}$
$I_{RRM}$	Max. Reverse Recovery Current	$di_F/dt=-200\text{A}/\mu\text{s}, T_J=125^\circ\text{C}$	--	50	--	A
		$V_R=850\text{V}, I_F=200\text{A}$	--	900	--	ns
$I_{RRM}$	Max. Reverse Recovery Current	$di_F/dt=-1000\text{A}/\mu\text{s}, T_J=125^\circ\text{C}$	--	150	--	A

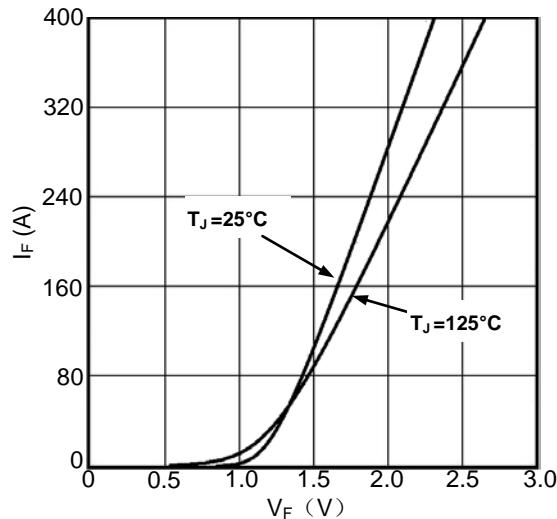
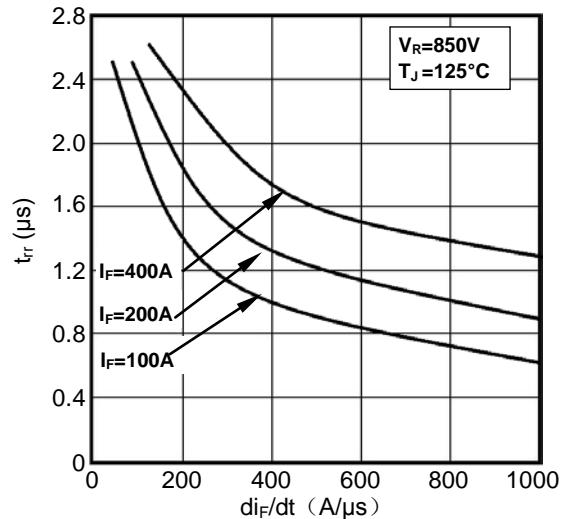
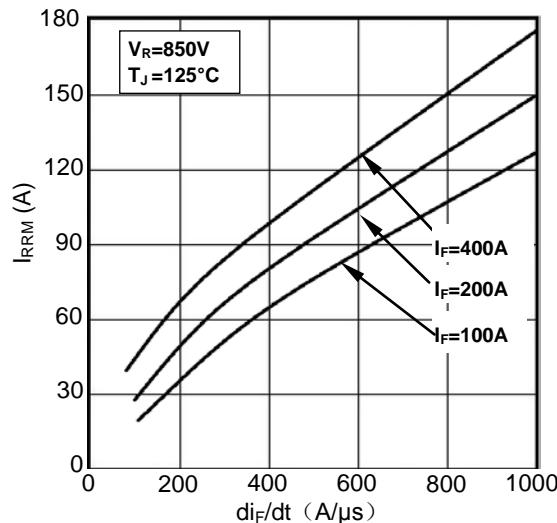
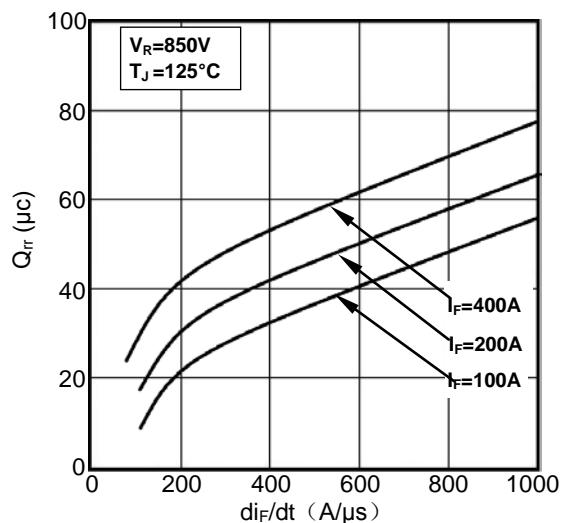


Figure 1. Forward Voltage Drop vs Forward Current

Figure 2. Reverse Recovery Time vs  $di_F/dt$ Figure 3. Reverse Recovery Current vs  $di_F/dt$ Figure 4. Reverse Recovery Charge vs  $di_F/dt$

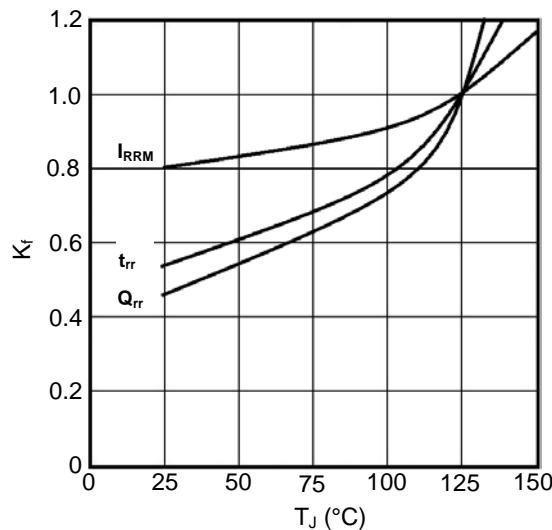


Figure5. Dynamic Parameters vs Junction Temperature

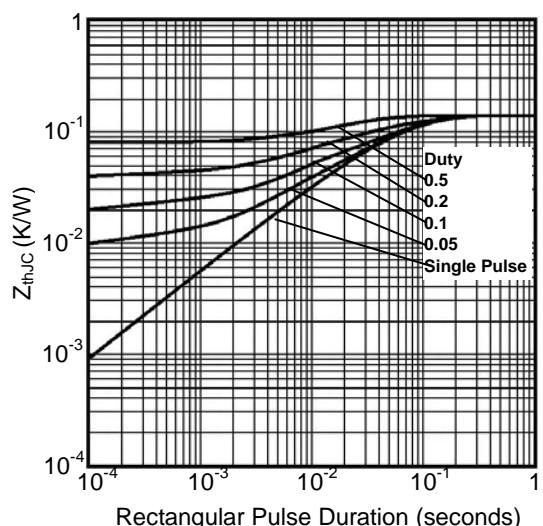
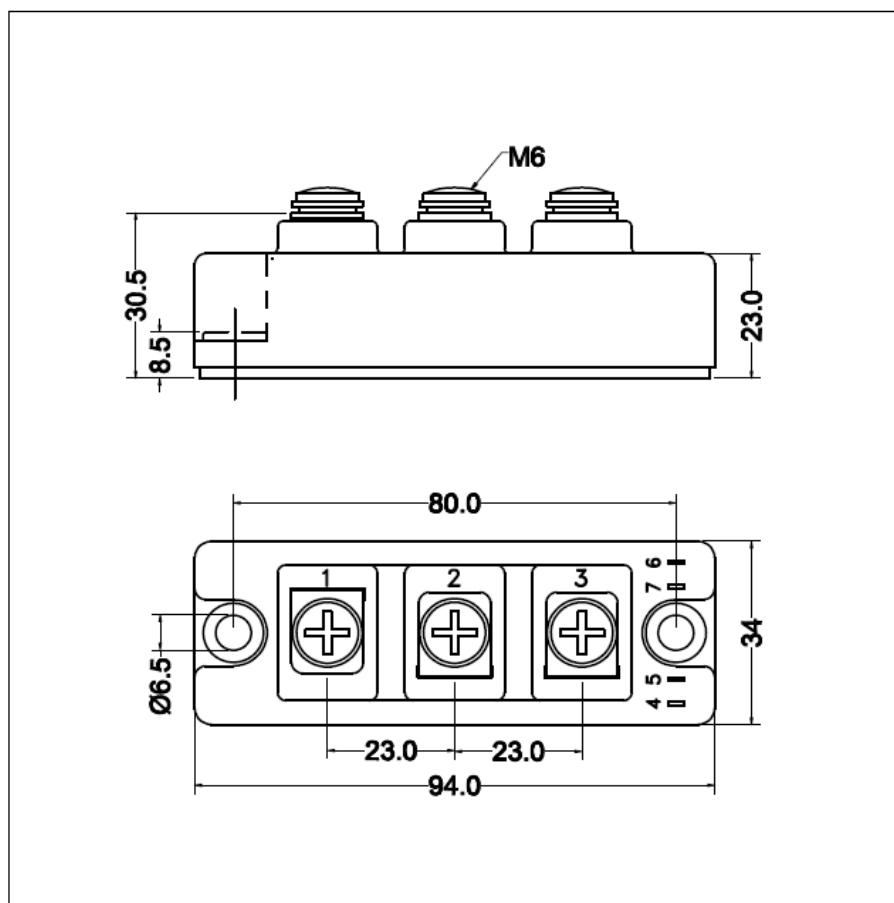


Figure6. Transient Thermal Impedance



Dimensions (mm)  
Figure7. Package Outline